

FDC6901L Integrated Load Switch

Features

- Three Programmable Slew Rates
- Reduces Inrush Current
- Minimizes EMI
- Normal Turn-Off Speed
- Low-Power CMOS Operates Over Wide Voltage Range
- High Performance Trench Technology for Extremely low $R_{DS(ON)}$
- RoHS Compliant

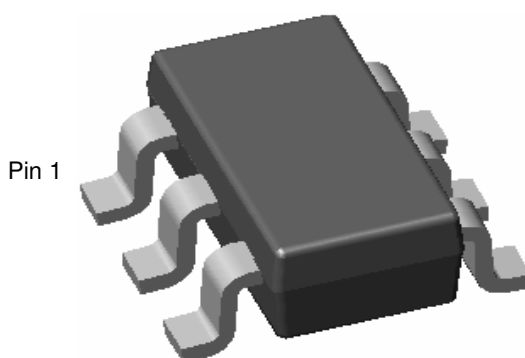
Applications

- Load switch
- Power management



General Description

This device is particularly suited for compact power management. In portable electronic equipment where 2.5V to 6V input capability is needed. This load switch integrates a Slew Rate Control Driver that drives a P-Channel Power MOSFET in one tiny SuperSOT™-6 package. The integrated slew rate control driver is specifically designed to control the turn on of the P-Channel MOSFET in order to limit the inrush current in battery switching applications with high capacitance loads. For turn-off, the IC pulls the MOSFET gate up quickly.

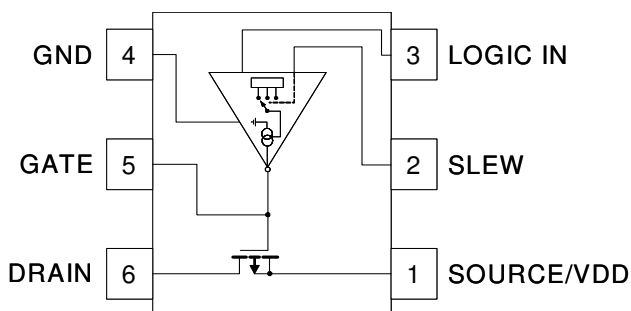


SuperSOT™-6

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity
.901	FDC6901L	7"	8mm	3000 units

Pin Configuration



Absolute Maximum Ratings

Parameter	Min.	Max.	Unit
Supply Voltage	-0.5	10	V
DC Input Voltage (Logic Inputs)	-0.7	9	V
Power Dissipation			
Storage Junction Temperature	-55	150	°C
Thermal Resistance, Junction to Ambient		180	°C/W
Thermal Resistance, Junction to Case		60	°C/W

Recommended Operating Range

Parameter	Min.	Max.	Unit
Supply Voltage	2.7	6	V
Operating Junction Temperature	-55	150	°C

Electrical Characteristics

$T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Logic Levels						
Logic High Input Voltage	V_{IH}	$V_{DD} = 2.7\text{V to }6.0\text{V}$	70% V_{DD}			V
Logic Low Input Voltage	V_{IL}	$V_{DD} = 2.7\text{V to }6.0\text{V}$			25% V_{DD}	V
Off Characteristics - Slew Rate Control Driver						
Supply Input Breakdown Voltage	BV_{DG}	$I_{DG} = 10\mu\text{A}$, $V_{IN} = 0\text{V}$, $V_{SLEW} = 0\text{V}$	9			V
Slew Input Breakdown Voltage	BV_{SLEW}	$I_{SLEW} = 10\mu\text{A}$, $V_{IN} = 0\text{V}$	9			V
Logic Input Breakdown Voltage	BV_{IN}	$I_{IN} = 10\mu\text{A}$, $V_{SLEW} = 0\text{V}$	9			V
Supply Input Leakage Current	I_{RDG}	$V_{DG} = 8\text{V}$, $V_{IN} = 0\text{V}$, $V_{SLEW} = 0\text{V}$			100	nA
Slew Input Leakage Current	I_{RSLEW}	$V_{SLEW} = 8\text{V}$, $V_{IN} = 0\text{V}$			100	nA
Logic Input Leakage Current	I_{RIN}	$V_{IN} = 8\text{V}$, $V_{SLEW} = 0\text{V}$			100	nA
Off Characteristics - Slew Rate Control Driver + P-Channel MOSFET						
MOSFET Breakdown Voltage	BV_{DSS}	$I_D = -250\mu\text{A}$	9			V
MOSFET Leakage Current	I_{DSS}	$V_R = 16\text{V}$			100	nA
On Characteristics - Slew Rate Control Driver						
Output/Gate Current	I_G	$I_D = -250\mu\text{A}$	Slew Pin = Open	90		μA
			Slew Pin = GND	1		μA
			Slew Pin = V_{DD}	10		nA

Electrical Characteristics Cont.

$T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
On Characteristics - P-Channel MOSFET						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = -250\mu A$	-0.6	-1	-1.5	V
Static Drain-Source On Resistance	$R_{DS(ON)}$	$V_{GS} = -4.5V$, $I_D = -1.5A$		120	145	mΩ
		$V_{GS} = -2.5V$, $I_D = -1.2A$		170	210	mΩ
On Characteristics - Slew Rate Control Driver + P-Channel MOSFET						
Dropout Voltage	V_{DROP}	$V_{DD} = 6V$, $V_{IN} = 2.5V$ to $6V$, $I_L = 1.5A$		160	300	mV
		$V_{DD} = 6V$, $V_{IN} = 2.5V$ to $6V$, $I_L = 1.2A$		130	300	mV
Load Switch On Resistance	R_{ON}	$V_{DD} = 6V$, $V_{IN} = 2.5V$ to $6V$, $I_L = 1.5A$		105	180	mΩ
		$V_{DD} = 6V$, $V_{IN} = 2.5V$ to $6V$, $I_L = 1.2A$		110	210	mΩ
Load Current	I_{LOAD}	$V_{GS} = 2.5\text{ V}$, $V_{DS} = 6\text{ V}$	3			A
P-Channel Switching Times ($V_{SUPPLY} = 5.5V$, $V_{DD} = 5.5V$, Logic IN = 5.5V, $I_{LOAD} = 1.5A$)						
Delay On Time	t_{dON}	Slew Pin = Open		6.2		μs
		Slew Pin = GND		42		μs
		Slew Pin = V_{DD}		115		μs
V_{OUT} Rise Time	t_R	Slew Pin = Open		6.75		μs
		Slew Pin = GND		124		μs
		Slew Pin = V_{DD}		162		μs
Output Slew Rate	dv/dt	Slew Pin = Open		600		V/ms
		Slew Pin = GND		41		V/ms
		Slew Pin = V_{DD}		24		V/ms

Typical Characteristics

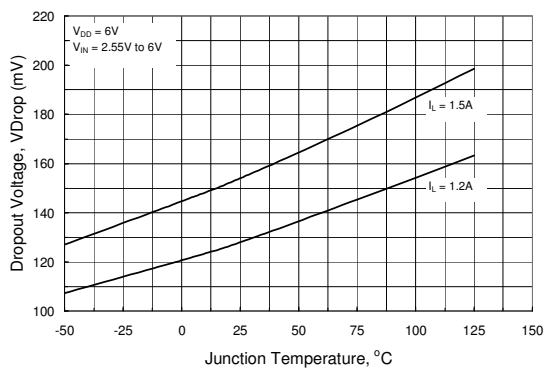


Figure 1. Dropout Voltage vs. Temperature (SLEW = OPEN)

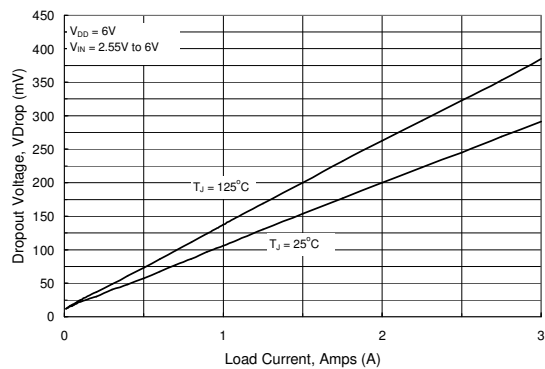


Figure 2. Dropout Voltage vs. Load Current (SLEW = OPEN)

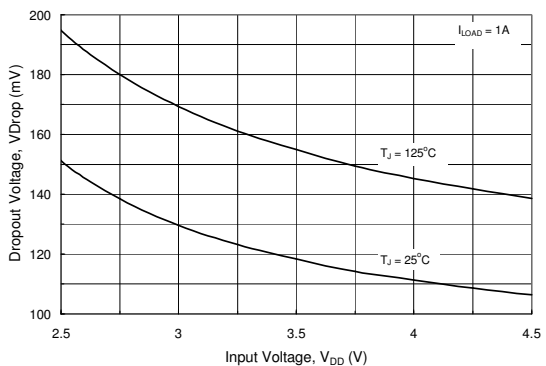


Figure 3. Dropout Voltage vs. Input Voltage (SLEW = OPEN)

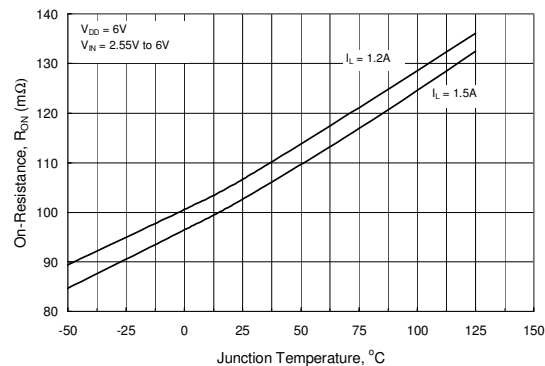


Figure 4. On Resistance vs. Temperature (SLEW = OPEN)

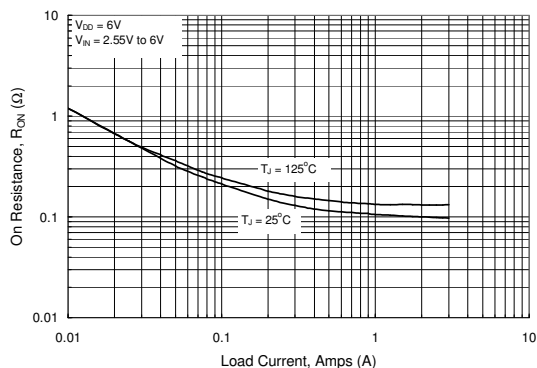


Figure 5. On Resistance vs. Load Current (SLEW = OPEN)

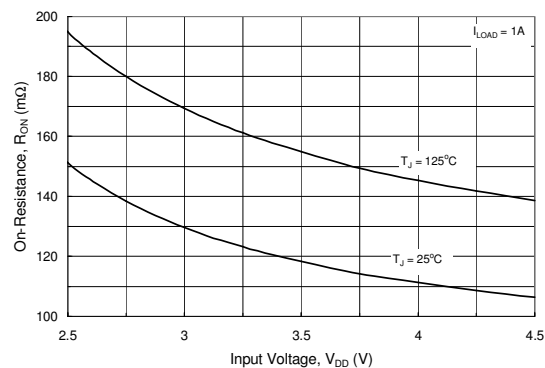


Figure 6. On Resistance vs. Input Voltage (SLEW = OPEN)

Typical Characteristics

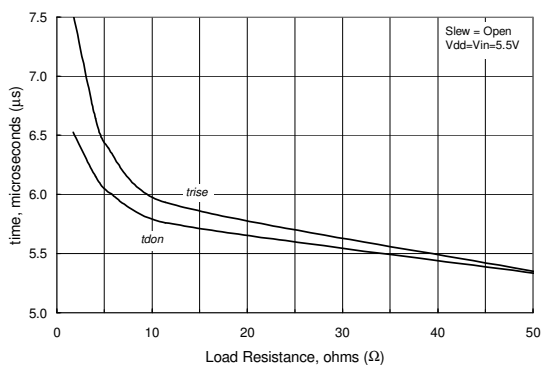


Figure 7. Switching Time vs. Load Resistance (SLEW = OPEN)

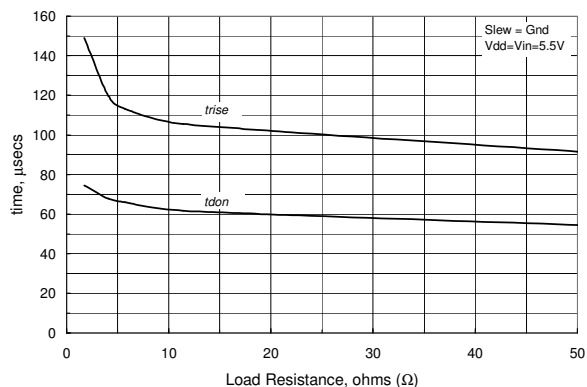


Figure 8. Switching Time vs. Load Resistance (SLEW = GROUND)

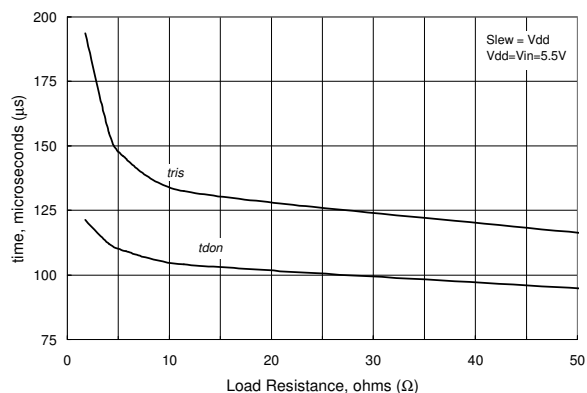


Figure 9. Switching Time vs. Load Resistance (SLEW = V_{DD})

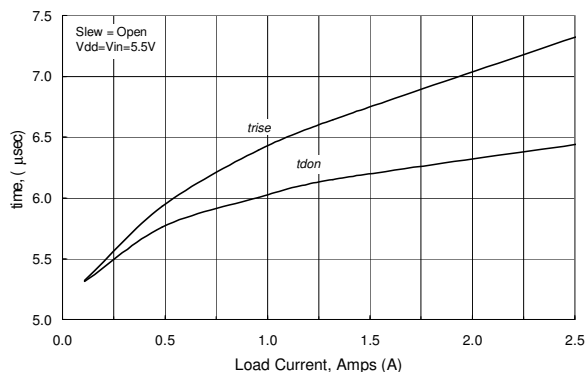


Figure 10. Switching Time vs. Load Current (SLEW = OPEN)

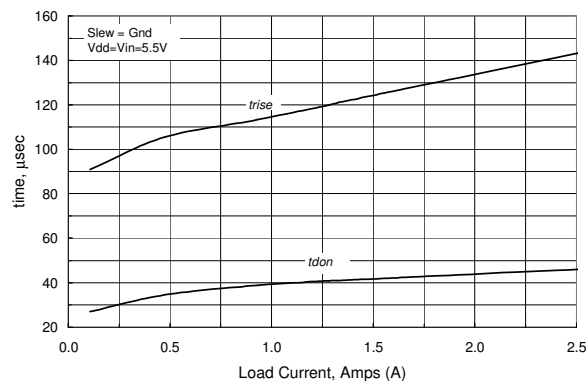


Figure 11. Switching Time vs. Load Current (SLEW = GROUND)

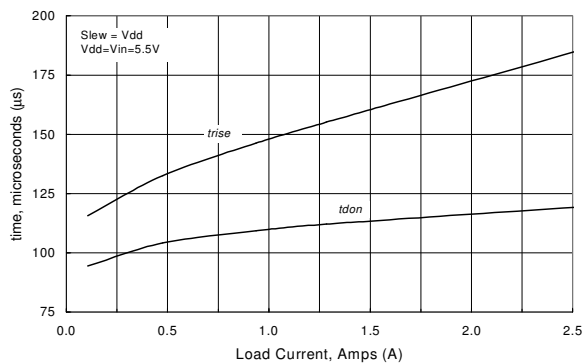
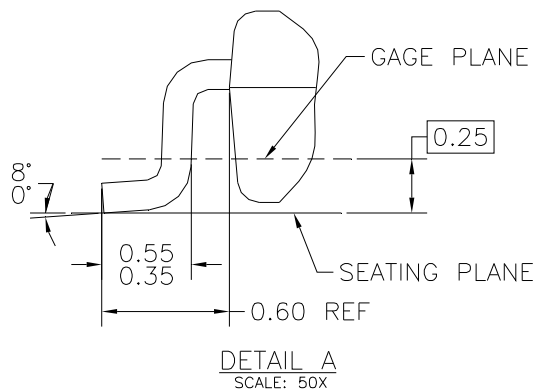
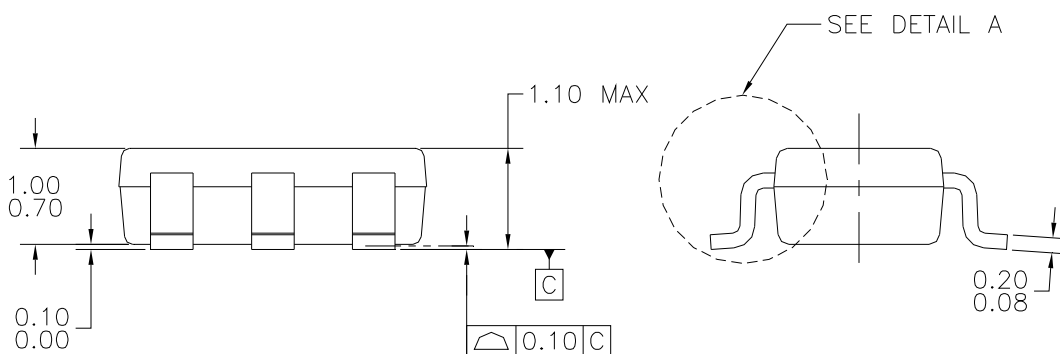
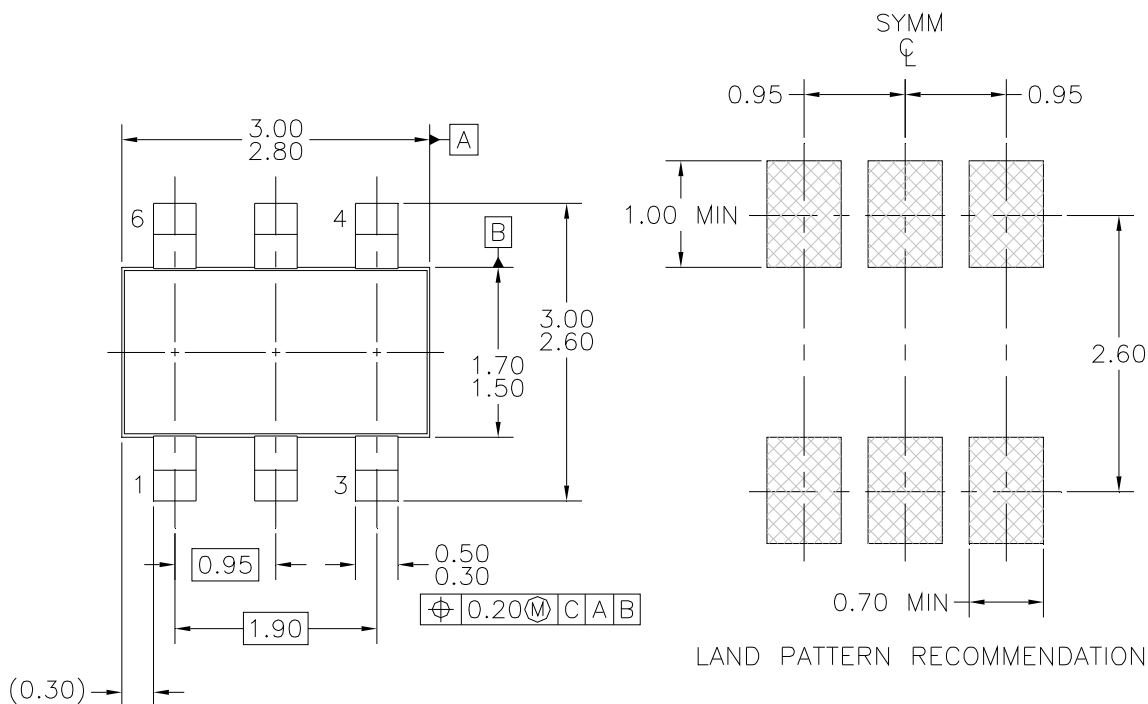


Figure 12. Switching Time vs. Load Current (SLEW = V_{DD})

Dimensional Outline and Pad Layout



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MO-193. VAR. AA, ISSUE C, DATED JANUARY 2000.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.

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